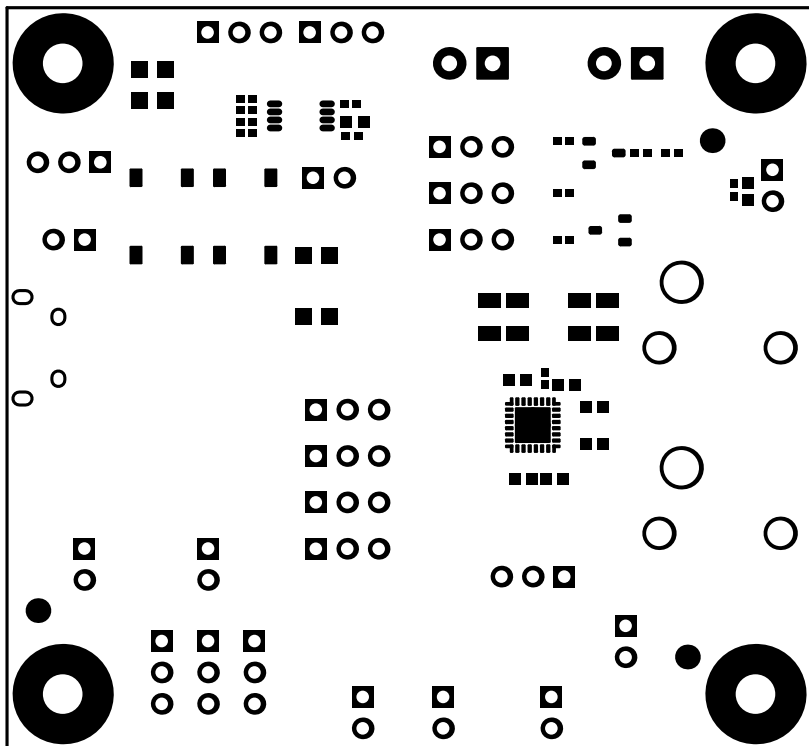
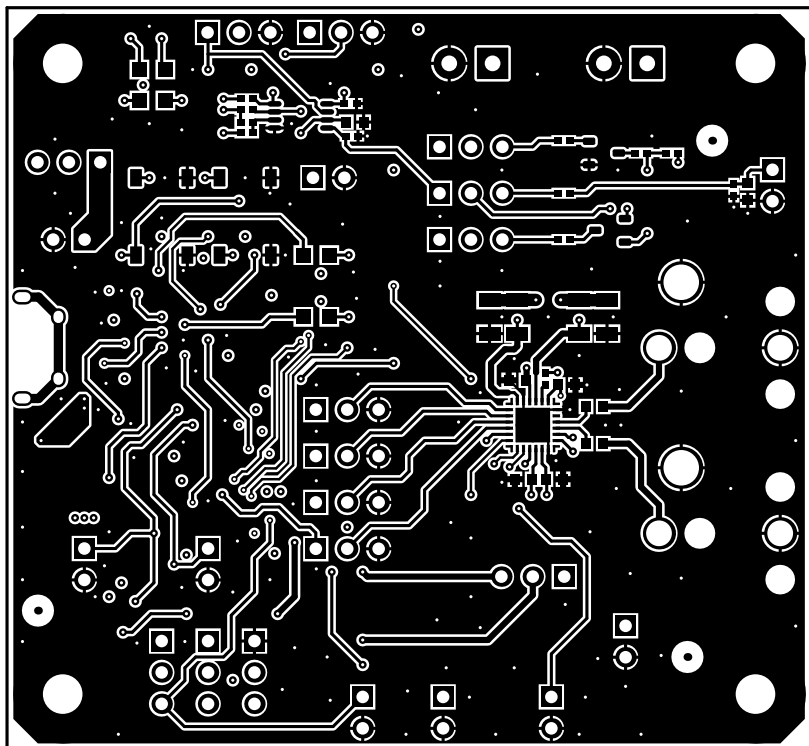


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01529	REV: B	SVN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 3/9/2018 6:38:20 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01529	REV: B	SVN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 3/9/2018	6:38:21 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-01529

REV: B

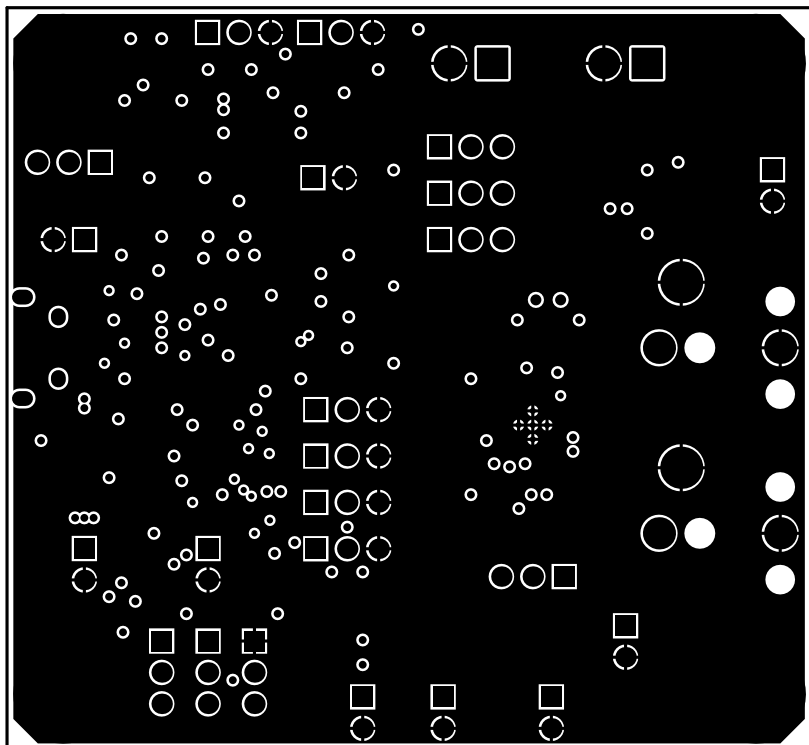
SVN REV: Not In VersionControl

LAYER NAME = Top Layer

PLOT NAME = Top Layer

GENERATED : 3/9/2018 6:38:21 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-01529

REV: B

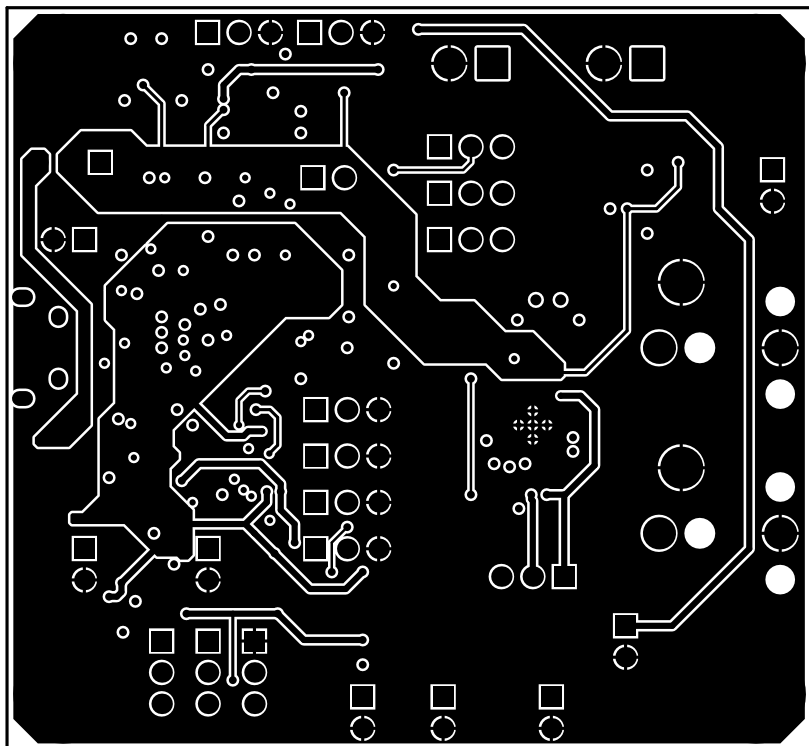
SVN REV: Not In VersionControl

LAYER NAME = Signal Layer 1

PLOT NAME = Signal 1

GENERATED : 3/9/2018 6:38:22 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-01529

REV: B

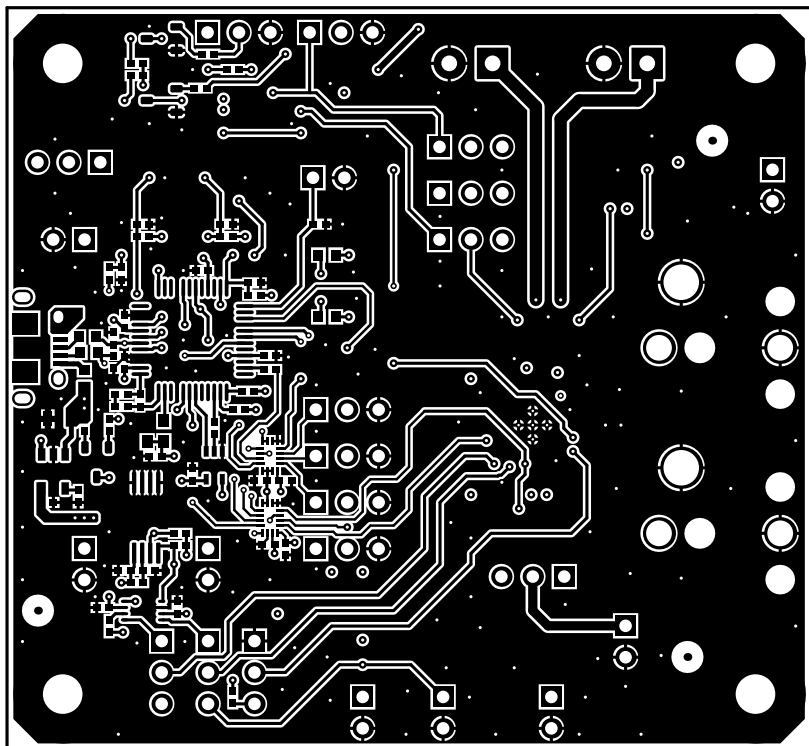
SVN REV: Not In VersionControl

LAYER NAME = Signal Layer 2

PLOT NAME = Signal 2

GENERATED : 3/9/2018 6:38:23 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-01529

REV: B

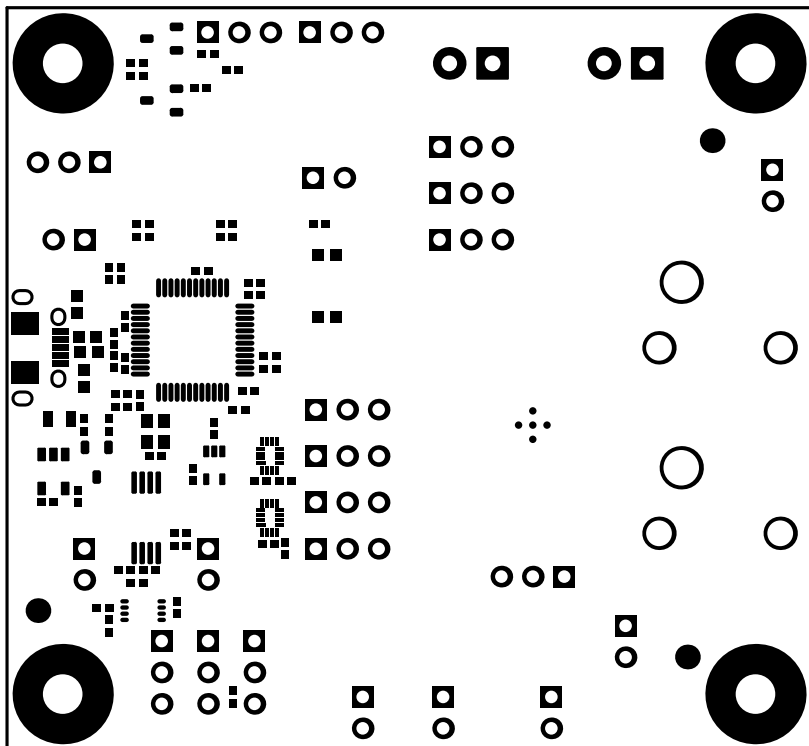
SVN REV: Not In VersionControl

LAYER NAME = Bottom Layer

PLOT NAME = Bottom Layer

GENERATED : 3/9/2018 6:38:24 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-01529

REV: B

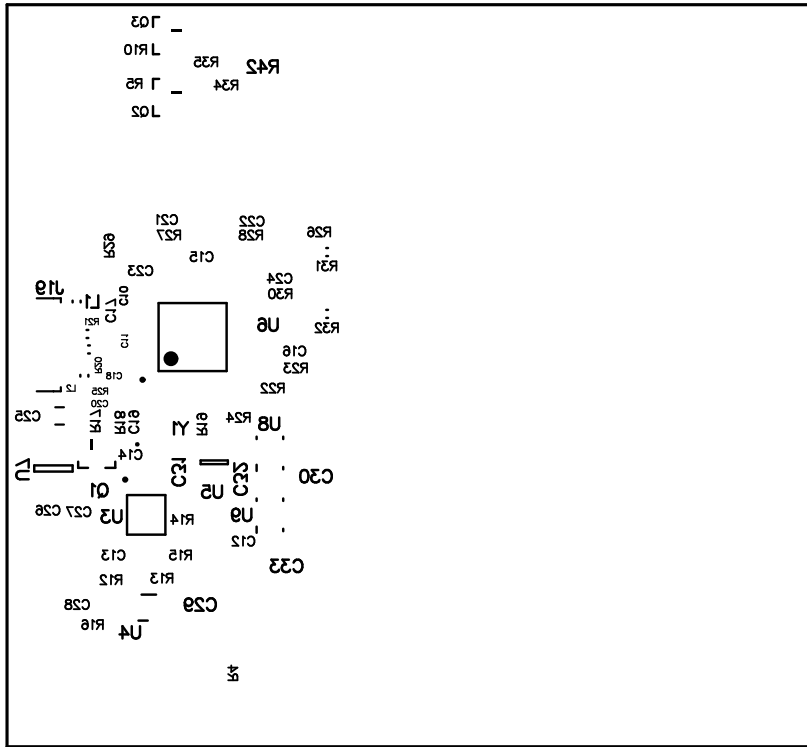
SVN REV: Not In VersionControl

LAYER NAME = Bottom Solder

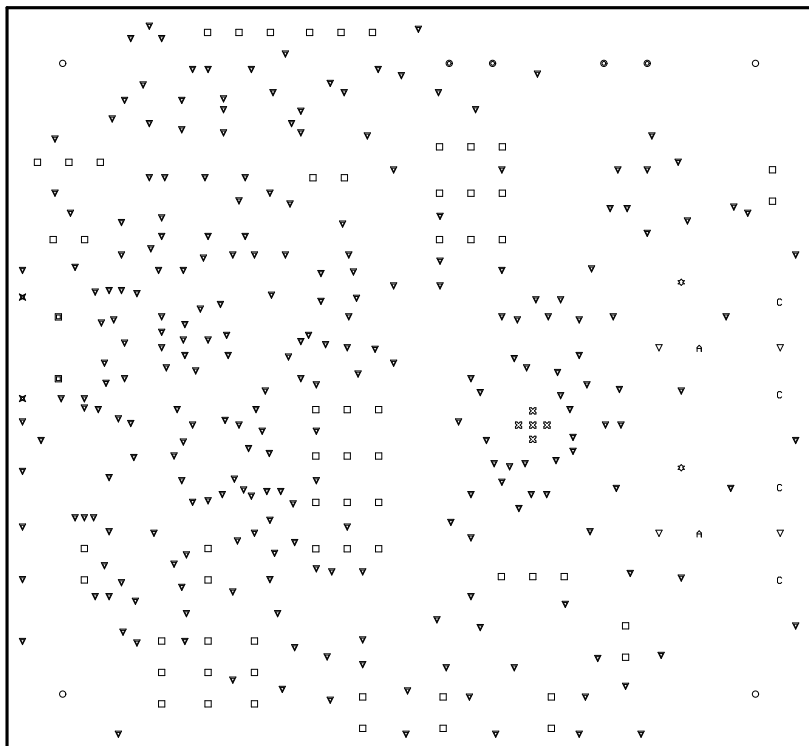
PLOT NAME = Bottom Solder Mask

GENERATED : 3/9/2018 6:38:25 PM

TEXAS INSTRUMENTS



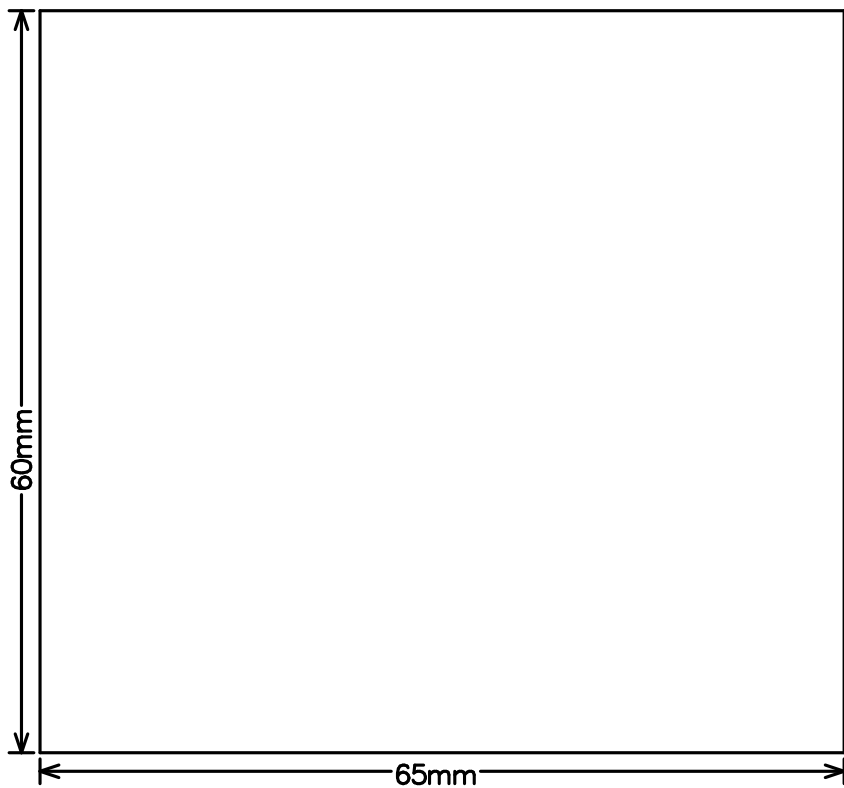
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01529	REV: B	SVN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 3/9/2018	6:38:25 PM	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair
C	4	1.980mm (77.95mil)	NPTH	Round	Top Layer - Bottom Layer
A	2	2.080mm (81.89mil)	NPTH	Round	Top Layer - Bottom Layer
X	5	0.200mm (7.87mil)	PTH	Round	Top Layer - Bottom Layer
▼	247	0.254mm (10.00mil)	PTH	Round	Top Layer - Bottom Layer
□	60	1.016mm (40.00mil)	PTH	Round	Top Layer - Bottom Layer
⊙	4	1.270mm (50.00mil)	PTH	Round	Top Layer - Bottom Layer
▽	4	2.080mm (81.89mil)	PTH	Round	Top Layer - Bottom Layer
☆	2	2.870mm (112.99mil)	PTH	Round	Top Layer - Bottom Layer
○	4	3.200mm (125.98mil)	PTH	Round	Top Layer - Bottom Layer
■	2	0.800mm (31.50mil)	PTH	Slot	Top Layer - Bottom Layer
✕	2	0.800mm (31.50mil)	PTH	Slot	Top Layer - Bottom Layer
	336 Total				

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01529	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 3/9/2018	6:38:26 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01529	REV: B	SVN REV: Not In VersionControl
LAYER NAME =	M2 Board Dimensions		
PLOT NAME = Board Dimensions	GENERATED : 3/9/2018	6:38:28 PM	TEXAS INSTRUMENTS

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